

Resonac Holdings Corporation

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Resonac and Infineon Technologies Strengthen Cooperation in SiC Materials for Power Semiconductors

Resonac Corporation (Resonac) (President: Hidehito Takahashi) has concluded new multiyear contracts with Infineon Technologies AG (Infineon), a German semiconductor manufacturer providing power semiconductors worldwide, to continue supplying SiC materials for power semiconductors to Infineon and cooperatively developing technologies related to SiC materials. Resonac concluded these new contracts in order to complement and expand the preceding supply and joint development contracts concluded in 2021*1, thereby strengthening the partnership with Infineon.

Resonac expects this partnership will enable Infineon to apply Resonac's SiC materials to various power semiconductor products, and now Resonac plans to provide Infineon with SiC materials of 200mm (8-inch) diameter, in addition to those of 150mm (6-inch) diameter. Furthermore, Resonac will accelerate improvement in technologies for and product quality of SiC epitaxial wafers through reinforced joint development activities with Infineon. Resonac and Infineon are confident that the strengthened partnership of the two companies will support rapid growth of the market for SiC materials, which are next-generation materials for semiconductors, and contribute to stabilization of the supply chain of SiC-based power semiconductors.

The Resonac Group aims to contribute to sustainable development of global society as a "Co-creative chemical company," and the Group positions its SiC epitaxial wafer business as a next-generation business because SiC-based power semiconductor realizes efficient use of energy. Under a motto of "Best in Class," the Resonac Group will continue providing the market with high-performance and highly-reliable SiC products, thereby contributing to the proliferation of SiC power semiconductors.

*1: "Showa Denko and Infineon Technologies Conclude Supply Contract and Development Agreement" announced on May 6, 2021.

For reference, we attach Infineon's press release as follows.

Infineon and Resonac announce the expansion of their cooperation and a new multi-year agreement for delivery of silicon carbide (SiC) materials

Munich, Germany – 12 January 2023 – Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) is extending its cooperation with silicon carbide (SiC) suppliers. The German-based semiconductor manufacturer has signed a new multi-year-supply and cooperation agreement with Resonac Corporation (formerly Showa Denko K.K.), complementing and expanding the announcement of 2021. The new set of contracts will deepen the long-term partnership on

SiC material. According to the agreement, Resonac will supply Infineon with SiC materials for the production of SiC semiconductors, covering a double-digit share of the forecasted demand for the next decade. While the initial phase focuses on 6" SiC material supply, Resonac will also support Infineon's transition to 8" wafer-diameter during the later years of the agreement. As part of the cooperation, Infineon will provide Resonac with intellectual property relating to SiC material technologies. The Infineon - Resonac partnership contributes to supply chain stability and will support the rapid growth of the emerging semiconductor material SiC.

"The demand for SiC is growing rapidly and we are preparing for this development with a significant expansion of our manufacturing capacities," said Angelique van der Burg, Chief Procurement Officer at Infineon. "We are pleased to deepen our collaboration with Resonac and strengthen the partnership between our two companies."

"The business opportunities in the area of renewable energy generation and storage, electromobility and infrastructure are enormous for the years to come. Infineon is doubling down on its investments into SiC technology and product portfolio, to proliferate the most comprehensive product offering to its customers. We are very happy that our partnership with Resonac will strongly support our market-leading position," said Peter Wawer, President of Infineon's Industrial Power Control division.

"We are pleased to team-up with Infineon as a global leader in power semiconductors in order to meet the growing demand for SiC in the years to come. We will continuously improve our Best-in-Class SiC material and develop the next generation of 8" wafer technology. We value Infineon as an excellent partner in this regard," said Jiro Ishikawa, Executive Adviser of Device Solutions Business Unit at Resonac.

Infineon is currently expanding its SiC manufacturing capacity in order to reach a market share of 30 percent by the end of the decade. Infineon's SiC manufacturing capacity is about to increase tenfold by 2027. A new plant in Kulim is scheduled to start production in 2024. Today, Infineon already provides SiC semiconductors to more than 3,600 customers worldwide.

About Infineon

Infineon Technologies AG is a global semiconductor leader in power systems and IoT. Infineon drives decarbonization and digitalization with its products and solutions. The company has around 56,200 employees worldwide and generated revenue of about €14.2 billion in the 2022 fiscal year (ending 30 September). Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the OTCQX International over-the-counter

market (ticker symbol: IFNNY).

Further information is available at www.infineon.com

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